



**PATENT APPLICATION**

In re the Application of:

Confirmation No.: 3797

Shingo MASUKO

Art Unit: 3729

Application No.: 10/777,135

Examiner: Donghai D. NGUYEN

Filed: February 13, 2004

Docket No.: 025720-00023

For: METHOD OF PACKAGING ELECTRONIC PARTS (As Amended)

**RESPONSE UNDER 37 C.F.R. § 1.121**

**MAIL STOP AMENDMENT**

Commissioner for Patents

P.O. Box 1450

Alexandria, Virginia 22313-1450

DATE: **April 21, 2006**

Sir:

This paper is in reply to the Office Action dated January 24, 2006.

Amendments to the **Title** are presented on page 2.

Amendments to the **Claims** begin on page 3.

Remarks/arguments begin on page 7.

**IN THE TITLE:**

Please amend the title as follows:

METHOD OF FABRICATING PACKAGING ELECTRONIC PARTS ~~PACKAGED~~  
~~WITH RESIN AND BASEBOARD USED FOR THE METHOD~~